### Purpose
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment
1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Yes</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Yes</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Liteon 65W EPS</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>DC cable</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>DC cable</td>
<td>1</td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td></td>
</tr>
</tbody>
</table>
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

Components and waste containing asbestos

Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>#1 Torx Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>#2 Slotted Screwdriver</td>
<td>2</td>
</tr>
<tr>
<td>#3 Micro shear</td>
<td>170II</td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disconnect the AC adapter cable. (see Figure 1 below)
2. Remove the access panel. (see Figure 2-3 below)
3. Remove the front bezel. (see Figure 4-5 below)
4. Remove HDD and HDD cable. (see Figure 6-9 below)
5. Remove HDD cage (see Figure 8 below)
6. Remove Memories. (see Figure 11-12 below)
7. Remove CPU HeatSink. (see Figure 13-14 below)
8. Remove system fan. (see Figure 15-17 below)
9. Remove PCIE cards. (see Figure 18-22 below)
10. Remove speaker, CPU and battery. (see Figure 23-29 below)
11. Remove MB. (see Figure 30-31 below)
12. Remove antenna cover and antenna cables. (see Figure 32-36 below)
13. Remove the covers. (see Figure 37-39 below)
14. Remove the PCA, and disconnect the cables. (see Figure 40-43 below)
15. Remove the Electrolytic Capacitors. (see Figure 44)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1: Disconnect the AC adapter cable.

Figure 2: Remove the thumb screw.

Figure 3: Remove the Access Panel.

Figure 4: Loose the anchor point of front bezel.

Figure 5: Remove the Front Bezel.

Figure 6: Disconnect HDD SATA cable.

PSG instructions for this template are available at EL-MF877-01
Figure 7 Disconnect HDD Power cable.

Figure 8 Loose the HDD latch and remove HDD.

Figure 9 Disconnect the cable from the HDD.

Figure 10 Loose the screw from HDD cage.

Figure 11 Loose the fixed feature of memory.

Figure 12 Remove the Memory from the board.

PSG instructions for this template are available at EL-MF877-01
Figure 13: Loose the screw of CPU HeatSink.

Figure 14: Remove the CPU HeatSink.

Figure 15: Disconnect the system fan cable.

Figure 16: Loose the screws of system fan cable.

Figure 17: Remove the system fan.

Figure 18: Disconnect the antenna cable.
Figure 19 Loose the WLAN card screw.

Figure 20 Remove the WLAN card.

Figure 21 Loose SSD card screw.

Figure 22 Remove the SSD card.

Figure 23 Disconnect the speaker cable.

Figure 24 Remove the plastic screw.
Figure 25 Remove the Speaker.

Figure 26 Rotate the handle and open it up.

Figure 27 Remove the CPU from the board.

Figure 28 Pull the battery towards the chassis wall.

Figure 29 Remove the battery from the system board.

Figure 30 Loose MB screw.
Figure 31 Remove the MB.
Figure 32 Loose the antenna cover hook.

Figure 33 Remove the antenna cover.
Figure 34 Loose the antenna cable tape.

Figure 35 Loose the antenna hook.
Figure 36 Remove the antenna.
Figure 37: Use Hammer and Slotted Screwdriver to destroy the Case (Use Delta EPS as an example).

Figure 38: Lift the cover off.

Figure 39: Lift the cover off the PCBA.

Figure 40: Remove the HeatSink from the board.

Figure 41: Remove the power cable from the board.

Figure 42: Remove the Socket from the board.

PSG instructions for this template are available at EL-MF877-01
Figure 43 Remove the Socket from the board.

Figure 44 Remove the Electrolytic Capacitors.